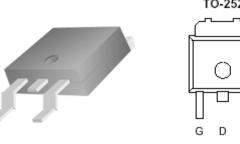
Analog Power AM35N03-59D

## N-Channel 30-V (D-S) MOSFET

These miniature surface mount MOSFETs utilize a high cell density trench process to provide low  $r_{DS(on)}$  and to ensure minimal power loss and heat dissipation. Typical applications are DC-DC converters and power management in portable and battery-powered products such as computers, printers, PCMCIA cards, cellular and cordless telephones.

battery-powered products such as computers,	30	$88 @ V_{GS} = 2.5V$	20
printers, PCMCIA cards, cellular and cordless			
telephones.		TO-252	2

- $\begin{array}{ll} \bullet & \quad Low \; r_{DS(on)} \; provides \; higher \; efficiency \; and \\ extends \; battery \; life \\ \end{array}$
- Low thermal impedance copper leadframe DPAK saves board space
- Fast switching speed
- High performance trench technology



**PRODUCT SUMMARY** 

 $r_{DS(on)} m(\Omega)$ 

 $59 @ V_{GS} = 4.5V$ 

 $I_{D}(A)$ 

24

Top View

 $V_{DS}(V)$ 

ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25 °C UNLESS OTHERWISE NOTED)					
Parameter		Symbol	Limit	Units	
Drain-Source Voltage		$V_{DS}$	30	V	
Gate-Source Voltage		$V_{GS}$	±12	V	
Continuous Drain Current <sup>a</sup>	T <sub>C</sub> =25°C	$I_D$	24	A	
Pulsed Drain Current <sup>b</sup>		$I_{DM}$	40	A	
Continuous Source Current (Diode Conduction) <sup>a</sup>		$I_S$	30	A	
Power Dissipation <sup>a</sup>	T <sub>C</sub> =25°C	$P_{\mathrm{D}}$	50	W	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	-55 to 175	°C	

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Maximum	Units		
Maximum Junction-to-Ambient <sup>a</sup>	$R_{ heta JA}$	50	°C/W		
Maximum Junction-to-Case	$R_{\theta JC}$	3.0	°C/W		

1

## Notes

- a. Surface Mounted on 1" x 1" FR4 Board.
- b. Pulse width limited by maximum junction temperature

Analog Power AM35N03-59D

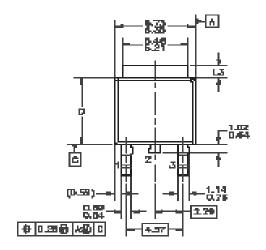
D		T4 C 114		Limits	;	Unit	
Parameter	Symbol	Test Conditions	Min	Тур	Max		
Static							
Gate-Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_D = 250 \text{ uA}$	0.6			V	
Gate-Body Leakage	Igss	$V_{DS} = 0 \text{ V}, V_{GS} = 12 \text{ V}$			±100	nA	
Zero Gate Voltage Drain Current	Idss	$V_{DS} = 24 \text{ V}, V_{GS} = 0 \text{ V}$			1	uA	
Zero Gate Voltage Drain Current	IDSS	$V_{DS} = 24 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55^{\circ}\text{C}$			25		
On-State Drain Current <sup>A</sup>	I <sub>D(on)</sub>	$V_{DS} = 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	34			A	
A		$V_{GS} = 4.5 \text{ V}, I_D = 12 \text{ A}$			59	mΩ	
Drain-Source On-Resistance <sup>A</sup>	TDS(on)	$V_{GS} = 2.5 \text{ V}, I_D = 10 \text{ A}$			88		
Forward Tranconductance <sup>A</sup>	gs	$V_{DS} = 15 \text{ V}, I_D = 12 \text{ A}$		22		S	
Diode Forward Voltage	$V_{\mathrm{SD}}$	$I_S = 24 \text{ A}, V_{GS} = 0 \text{ V}$		1.1		V	
Dynamic <sup>b</sup>							
Total Gate Charge	Qg	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V},$ $I_{D} = 10 \text{ A}$		6.3			
Gate-Source Charge	Qgs			0.9		nC	
Gate-Drain Charge	Qgd	ID – 10 A		1.9			
Turn-On Delay Time	td(on)			16			
Rise Time	tr	$V_{DD}$ = 25 V, $R_L$ = 25 $\Omega$ , $I_D$ = 24 A,		5			
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{GEN} = 10 V$		23		nS	
Fall-Time	$t_{\mathrm{f}}$			3			
Source-Ddrain Reverse Recovery Time	$t_{rr}$	$I_F = 24 \text{ A}, \text{ Di/Dt} = 100 \text{ A/uS}$		50			

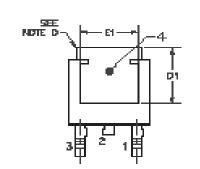
## Notes

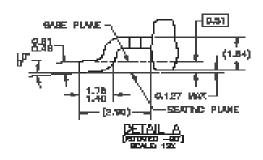
- a. Pulse test:  $PW \le 300us duty cycle \le 2\%$ .
- b. Guaranteed by design, not subject to production testing.

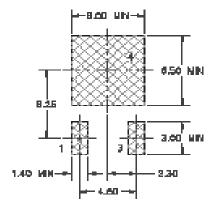
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## Package Information

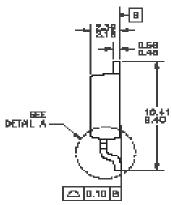








LAND PATTERN RECOMMENDATION



NOTES: UNLESS OTHERWISE SPECIFIED

- ALL DIPERSONS ARE IN ILLIMETERS.
  THIS PERSONCE CONFORMS TO JEDEC, TO-262,
  168ME C, VARIATION AA IN AB, DATED NOW 1989.
  DIMENSIONING AND TOLERANCING PER
- ASNE 714-04-1894.
  HEAT SINK TOP EDGE COLLD BE IN CHANFERED CORRERS OR EDGE PROTEURION.
  DIMENSIONS 13,0,61-601 TABLE:

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	0.4 []0.12	0.44 - 0.40
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